

## ABSTRACT OF THE DISCLOSURE

In the formation of through wirings in a silicon substrate and so forth, there was a need for the development of a technology that would allow metal to be reliably filled particularly in the vicinity of openings of through holes and other fine holes. This invention provides a metal filling method and member with filled metal sections in which, in the inflow and filling of a plating solution into through holes 11 of a substrate 10 by immersing said substrate 10 in heated and melted conductive metal, filled metal sections are formed by preliminarily forming a metal layer 15 on the inner surface of one of the ends of through holes 11 of this substrate 10 as well as on substrate top surface 13 around those openings, removing substrate 10 on which inflow and filling of the plating solution into through holes 11 has been completed from the plating solution, and then cooling to solidify the plating solution that has been filled into the through holes.